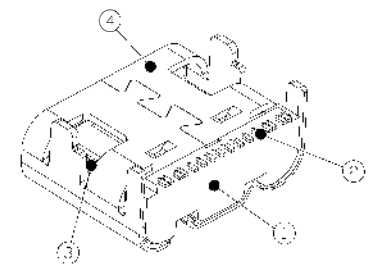
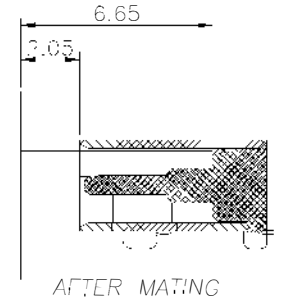
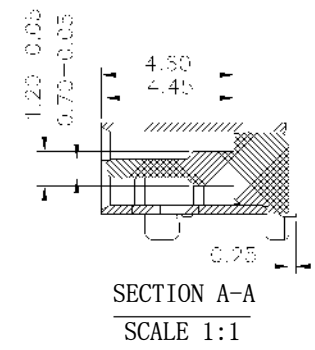
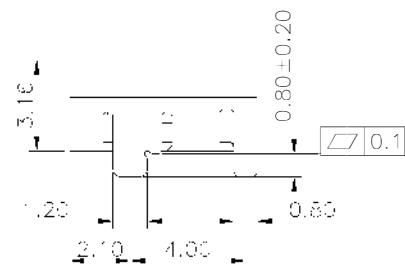


RECOMMENDED PCB LAYOUT(TOP VIEW)
THICKNESS 0.60MM:DEFAULT TOLERANCE:±0.05



USB TYPE C PIN ASSIGNMENTS

PIN NUMBER	SIGNAL NAME	PIN NUMBER	SIGNAL NAME
A1	GND	B12	GND
A4	VBUS	B9	VBUS
A5	CC1	B7	SUB2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Do2
A8	SP_1	B5	CC2
A9	VBUS	B4	VBUS
A12	GND	B	GND

PART NO.:
SEE THE PART NUMBER CODE

QUALITY SYMBOL

GENERAL TOLERANCES (UNLESS SPECIFIED)

x.xxxxx	± ---
x.xxx	± 0.10
x.xx	± 0.25
x.x	± 0.30
ANGULAR	± °

GOLDCONN TECHNOLOGIES COMPANY LIMITED

USB C F TYPE单排SMT6.5
四脚插板CONN一体成型

DRAWN BY: SAM DATE: 2020.03.12

CHECKED BY: JAY DATE: 2020.03.12

APPROVED BY: JACKY DATE: 2020.03.12

DESIGN UNITS: METRIC

SCALE: 11

THIRD ANGLE PROJECTION

REV	ECN No.	DATE	REMARK
A	NEW	2015.05.10	NEW RELEASE
B	ECN2003002	2020.03.12	修改图纸与实物相符

- NOTE:
- MATERIAL SPECIFICATION:
 - HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC LCP BK,J-94 V-0.
 - CON ACIS: COPPER ALLOY C1814
 - MID PLATE: STAINLESS STEEL SUS304
 - FRONT SHELL: STAINLESS STEEL SUS304
 - PLATING SPECIFICATION:
 - CONTACTS: Ni 50u" MIN. UNDER PLATED OVER ALL. Au PLATED ON THE FUNCTIONAL AREA OF CONTACT. (GOLD PLATING THICKNESS FOLLOW THE P/N) PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N
 - FRONT SHELL: Ni 30u" MIN. UNDER PLATED OVER ALL.
 - MID PLATE: CLEAR ONLY
 - MECHANICAL PERFORMANCE:
 - INSERTION FORCE: 0.3~2.0kgf.
 - REMOVAL FORCE: 0.8kgf~2.0kgf.
 - DURABILITY: 0000 Cycles.
 - ELECTRICAL PERFORMANCE:
 - CURRENT RATING:5.0A VOLTAGE RATING:5.0V
 - LLCR: VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX. SOLDER: 50mΩ/VAX. ICR MAX. CAPAC OF ALL PINS: 10mΩ.
 - INSULATION RESISTANCE: 100MΩ MIN
 - DIELECTRIC WITHSTAND VOLTAGE AC 100V FOR 1 MINUTE.
 - ENVIRONMENTAL PERFORMANCE:
 - OPERATING TEMPERATURE: -25°C~+85°C.
 - IR REFLOW: THE PEAK TEMPERATURE ON THE BOARD SHALL BE MAINTAINED FOR 10 SECONDS AT 260°C.
 - PART NUMBER CODE:
 - Z-CF055S X X 12 R-A-02
 - (1) (2) (3)